

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11)Publication

number: **01053105 A**

(43)Date of publication of

application: **23 . 02 . 01**

(51)Int. Cl

**H01L 21/60**

**G06T 7/00**

**G06T 1/00**

(21)Application number: **11222375**

(71)Applicant: **KAIJO CORP**

(22)Date of filing: **05 . 08 . 99**

(72)Inventor: **ISHII IWAO**

(54)BONDER

reference point on an IC chip 12. When completion of the movement is confirmed, the image pickup unit 25 delivers a command for fetching short position locating time and image signal to an image operation time of a lead locator by recognition unit 8. The image starting image accumulation of a recognition unit 8 delivers an image camera, when an XY table reaches a specified position, making the image storing time variable, and accumulating the image in short time thereby shortening the image storing time.

(57)Abstract:

PROBLEM TO BE SOLVED: To shorten position locating time and image operation time of a lead locator by recognition unit 8. The image starting image accumulation of a recognition unit 8 delivers an image camera, when an XY table reaches a specified position, making the image storing time variable, and accumulating the image in short time thereby shortening the image storing time.

SOLUTION: When a lead frame LF is carried onto a bonding stage 7 by means of a carrier 5, a controller 10 drives a driver 11 based on reference point information to move an image pickup unit 25 mounted on an XY table 4 to the coordinates of a

COPYRIGHT: (C)2001,JPO

